

REV	DESCRIPTION	DCN	DATE	BY/APPD
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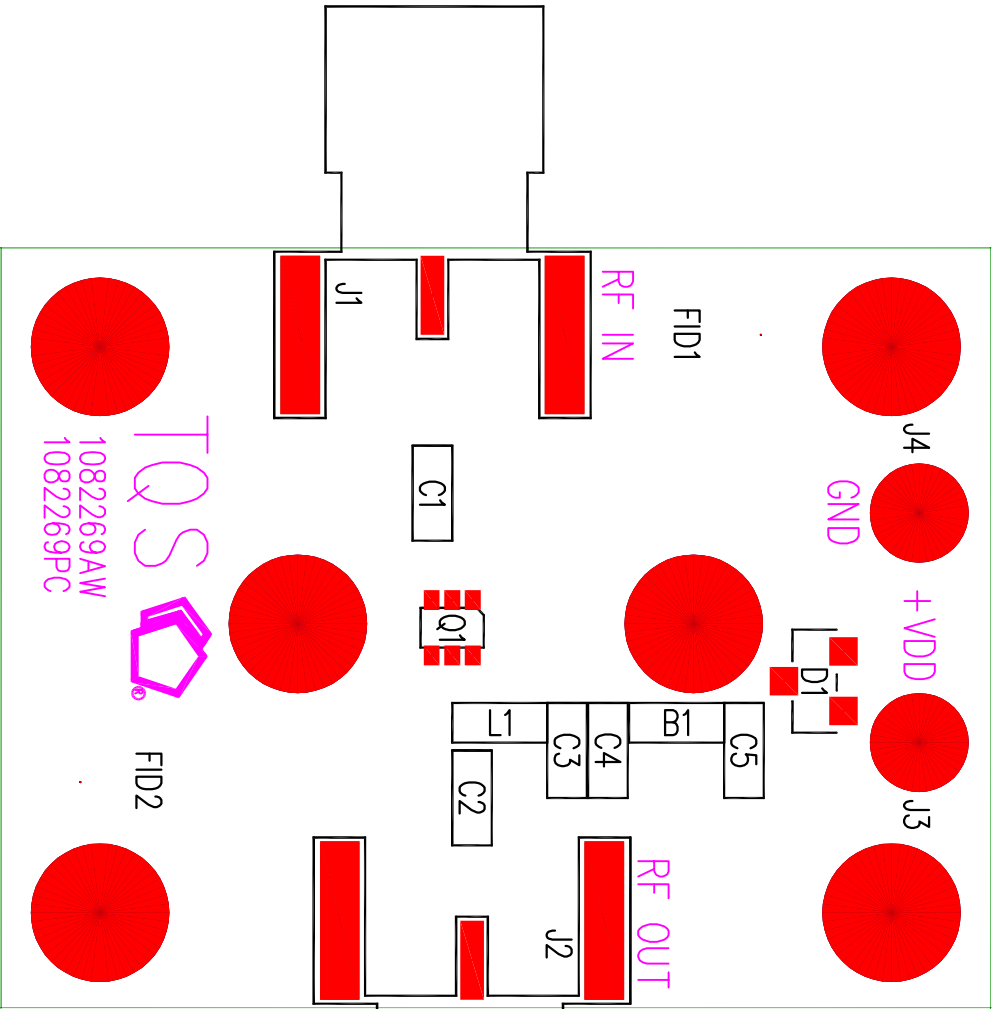
1

NOTES UNLESS OTHERWISE SPECIFIED:

- ASSEMBLE IAW J-STD-001 CURRENT REVISION. THE ASSEMBLY IS TO MEET THE INSPECTION CRITERIA OF IPC-A-610, CLASS 2, CURRENT REVISION.
- REFERENCE DOCUMENTS:  
SCHEMATIC DIAGRAM: 1082269SD.  
BILL OF MATERIAL: 1082269-001

- THIS ASSEMBLY CONTAINS ELECTROSTATIC SENSITIVE DEVICES; HANDLE IAW MIL-STD-1686, CLASS 2.
- SOLDER PASTE THICKNESS TO BE .006 ±.002.
- CONVECTION HEATING ONLY IS TO BE USED DURING SOLDER REFLOW, NO IR.
- BAG AND TAG (OR MARK CONTAINER) WITH PART NO. 1082269-001 AND CURRENT REV LEVEL.
- VIAS ARE OMITTED FOR CLARITY.
- PADS OF SMALL CHIP RESISTORS AND CAPACITORS ARE OMITTED FOR CLARITY.
- AQUEOUS CLEANING IS REQUIRED.
- NO-LOAD PARTS: ALL COMPONENTS WITH TRIQUINT PART NO. 445930-001. SEE BOM.
- ASSEMBLY INSTRUCTIONS:  
-STEP 1:  
ASSEMBLE ALL SMD DEVICES.  
-STEP 2:  
INSTALL J1, J2, J3, AND J4.

TOP SIDE



TRIQUINT SEMICONDUCTOR PROPRIETARY INFORMATION

QTY PER BASH	ITEM NO	PART IDENT NO	CAGE CODE	NOMENCLATURE OR DESCRIPTION	SPEC/STD
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UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.					
XX DEC. ± .02					
XXX DEC. ± .005					
MATERIAL					
SR K. KEISEN					
CHK					
ENG C. BLUM					
MFG					
FINISH PROTECTIVE FINISH					
SA					
TF					
CONV NO.					

PARTS LIST OR MATERIAL					
CIRCUIT CARD ASSEMBLY					
SOT 363					
SIZE CAGE CODE					
D 14482					
SCALE NONE					
V/V/O NO.					
SHEET 1 OF 1					

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D

D SIZE 7/8/08

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1082269

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